Product Bulletin

Document #:PB26151X
Issue Date:26 Mar 2024

Title of Change:	Packing material change to Moisture Barrier Bag from Vinyl bag
Effective date:	26 Mar 2024
Contact information:	Contact your local onsemi Sales Office or Keiji.Ogata@onsemi.com
Type of notification:	This Product Bulletin is for notification purposes only. onsemi will proceed with implementation of this change upon publication of this Product Bulletin.
Change Category:	Packaging Change
Change Sub-Category(s):	Shipping/Packaging/Marking

Sites Affected:

onsemi Sites	**External Foundry/Subcon Sites**
None	None

Description and Purpose:

onsemi would like to notify its customers of a packing material change to Moisture Barrier Bag from Vinyl bag for improvement of moisture properties of wafer sales products. Moisture Barrier Bag is the standard material for onsemi. There will be no other changes to the wafer/die material and BOM associated with this change.

	From	**To**
Packing material	Packing by Vinyl Bag	Packing by Moisture Barrier Bag

List of Affected Standard Parts:

Note*: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the* ***PCN Customized Portal****.*

LC4657C-Z2		